

**Maximum Ratings** (@T<sub>A</sub> = +25°C unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V <sub>DSS</sub>	-20	V
Gate-Source Voltage			V <sub>GSS</sub>	±12	V
Continuous Drain Current (Note 5) V <sub>GS</sub> = -4.5V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	-1.9 -1.5	A
Continuous Drain Current (Note 5) V <sub>GS</sub> = -4.5V	t ≤ 5s	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	-2.1 -1.65	A
Continuous Drain Current (Note 5) V <sub>GS</sub> = -2.5V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	-1.7 -1.3	A
Pulsed Drain Current	t <sub>p</sub> = 10μs		I <sub>DM</sub>	-4.0	A

**Thermal Characteristics**

Characteristic	Symbol	Value	Units
Power Dissipation (Note 5)	P <sub>D</sub>	0.85	W
Thermal Resistance, Junction to Ambient @T <sub>A</sub> = +25°C (Note 5)	R <sub>θJA</sub>	146	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 6)</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-20	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C T <sub>J</sub> = +125°C	I <sub>DSS</sub>	—	—	-1.0 -5.0	μA	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	—	—	±100	nA	V <sub>GS</sub> = ±12V, V <sub>DS</sub> = 0V
<b>ON CHARACTERISTICS (Note 6)</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	-0.45	—	-1.0	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	—	92	150	mΩ	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -950mA
			134	200		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -670mA
			180	240		V <sub>GS</sub> = -1.8V, I <sub>D</sub> = -200mA
Forward Transconductance	g <sub>FS</sub>	—	3.1	—	S	V <sub>DS</sub> = -10V, I <sub>D</sub> = -810mA
Diode Forward Voltage (Note 6)	V <sub>SD</sub>	—	—	-0.9	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = -360mA
<b>DYNAMIC CHARACTERISTICS</b>						
Input Capacitance	C <sub>iss</sub>	—	320	—	pF	V <sub>DS</sub> = -16V, V <sub>GS</sub> = 0V f = 1.0MHz
Output Capacitance	C <sub>oss</sub>	—	80	—	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	—	60	—	pF	

Notes: 5. Device mounted on FR-4 PCB with 1 inch square pads.  
6. Short duration pulse test used to minimize self-heating effect.

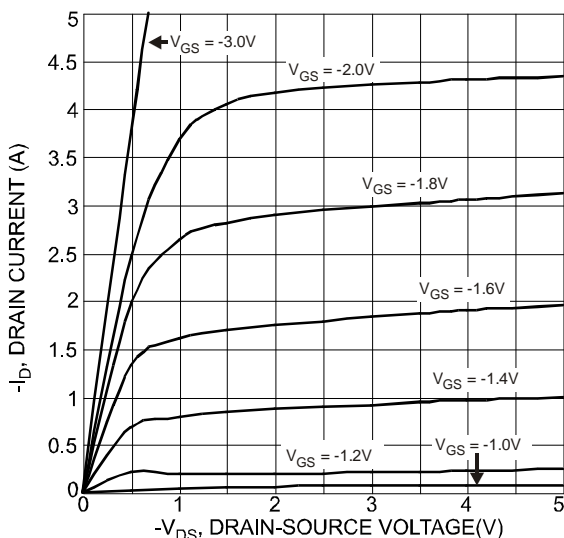


Fig. 1 Typical Output Characteristics

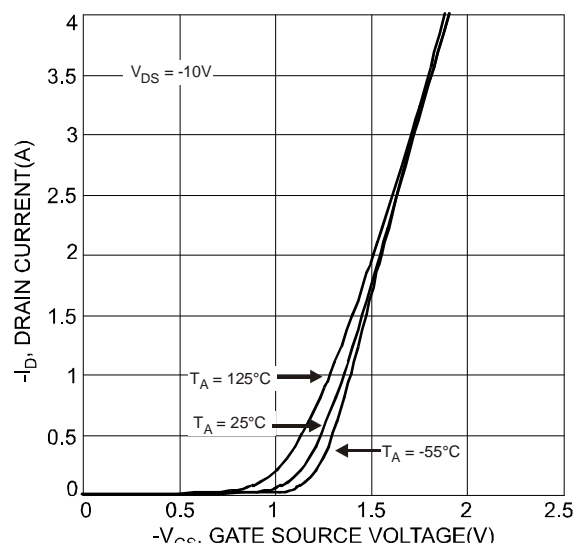


Fig. 2 Typical Transfer Characteristics

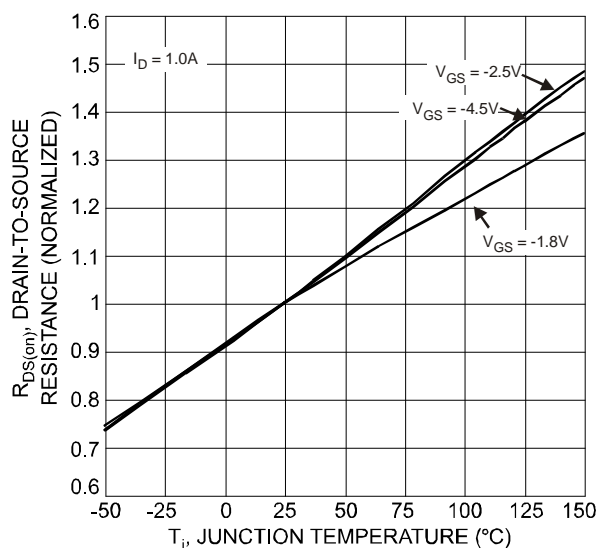


Fig. 3 On-Resistance Variation with Temperature

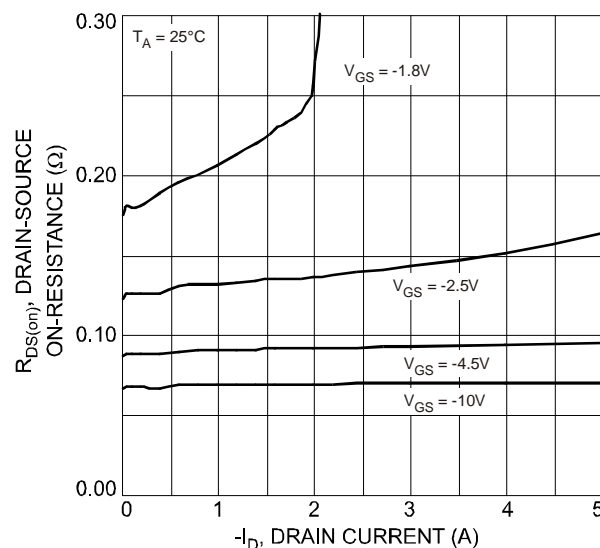


Fig. 4 On-Resistance vs. Drain Current and Gate Voltage

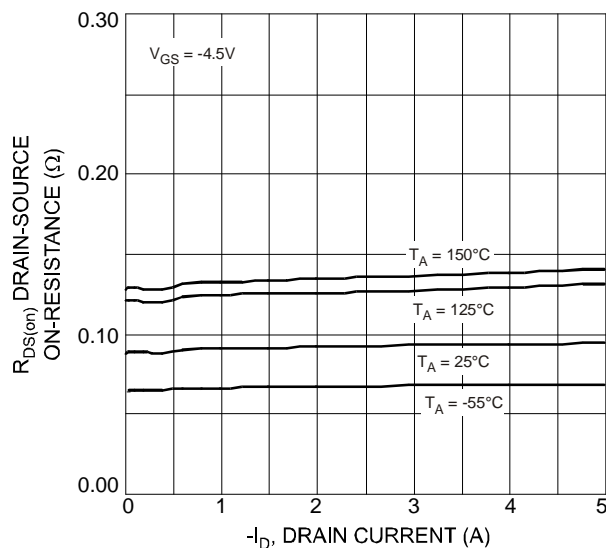


Fig. 5 Drain-Source On-Resistance vs. Drain Current and Temperature

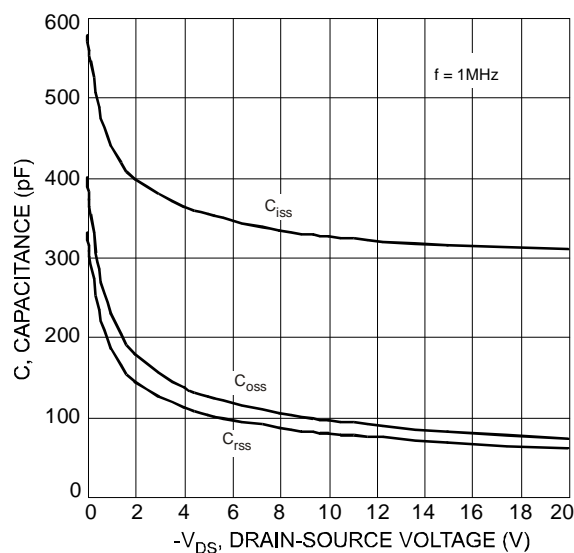


Fig. 6 Typical Capacitance

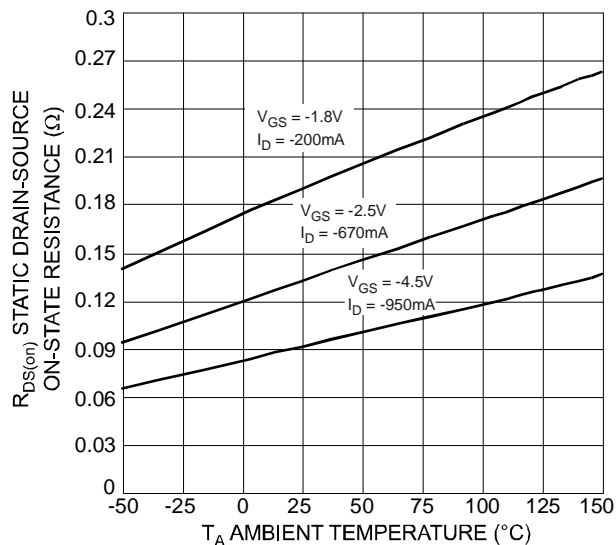


Fig. 7 Static Drain-Source On-State Resistance vs. Ambient Temperature

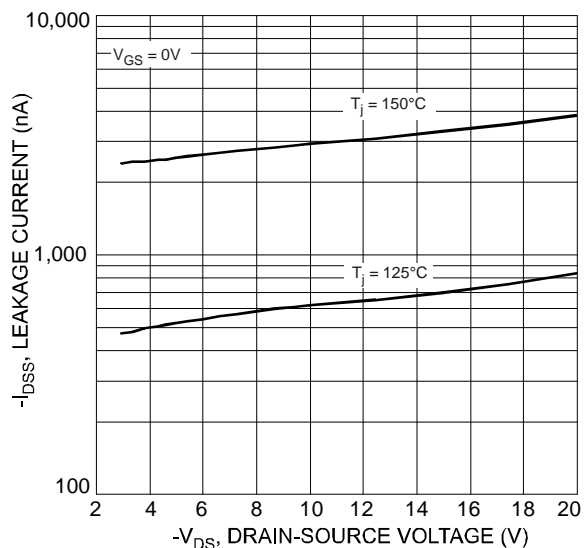


Fig. 8 Drain-Source Leakage Current vs. Voltage

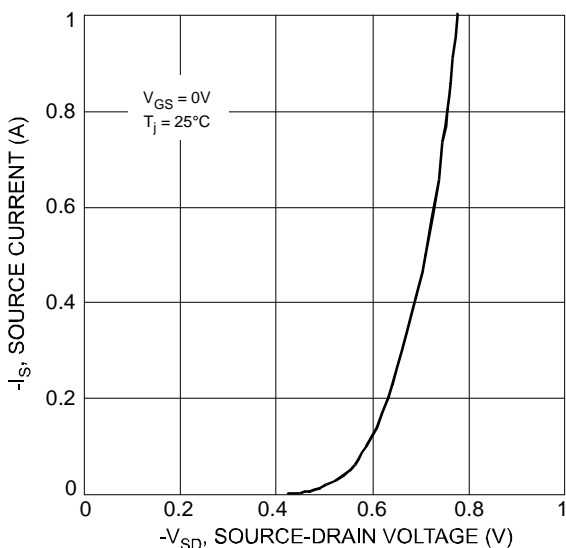


Fig. 9 Diode Forward Voltage vs. Current

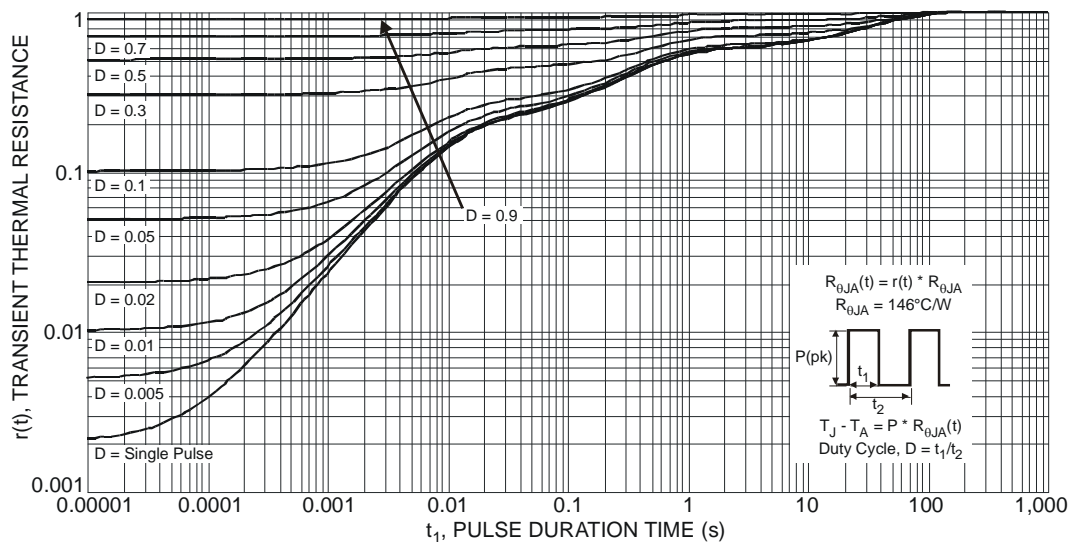
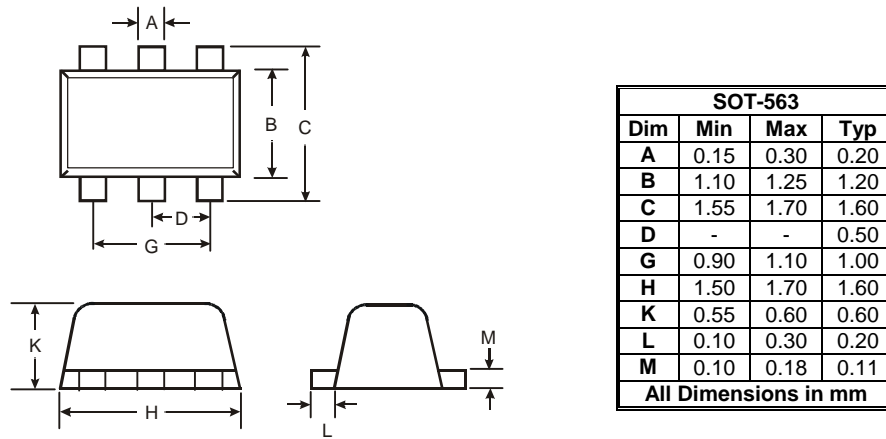


Fig. 10 Transient Thermal Response

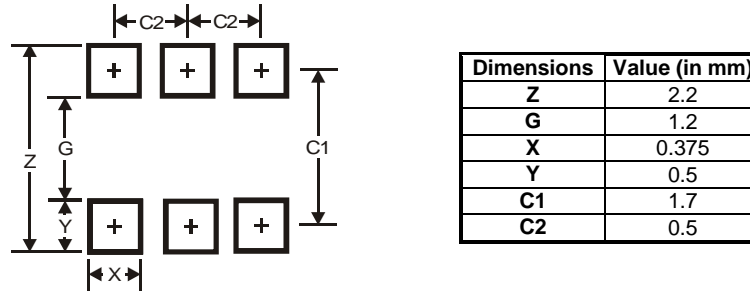
## Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for latest version.



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